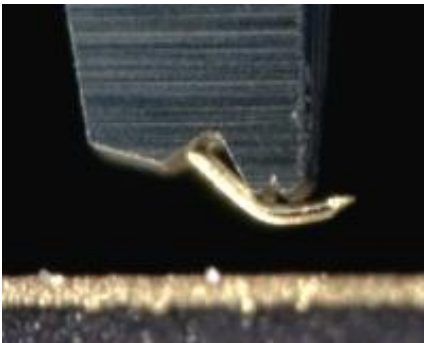


## TPT-application standard 25 $\mu$ gold wedge-wedge bonding

### Equipment:

- 25 $\mu$  gold wire, 100m at 2" spool
- Standard gold wedge tool
- Semiautomatic Wedge-Wedge Wire Bonder HB16



Gold Wedge Tool



Wedge-bonding



Wedge-Bond

### Bonding process:

- thread wire to the tip of wedge tool.
- program bond parameters and loop profile.
- after second bond clamp is closes, wire is cut.
- it is recommended to heat up bond surface up to 120°C.

### Advantages over ball-wedge bonding:

- Bonding on very small bond pads
- Flat and long loops possible.
- Gold and aluminum wire
- Aluminum wire without heating.

